



Overview of semiconductor reliability topics addressed imec

By

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Date/Time: November 11th, 1.00pm-2.00 pm

Room: MRGN 121



Abstract:

In this talk, I will outline the main activities we perform in the field of reliability at imec.

First, so-called time-zero reliability topics will be covered, where I will mainly address our activities in the field of thermo-mechanical and thermal challenges in advanced interconnects and packages.

Also, so-called time-driven reliability topics will be covered, where reliability concerns and challenges related to advanced FEOL, BEOL, fBEOL, 3D-packages and SiPho devices will be covered.

In the presentation, I will touch upon a broad range of topics while not going too much in detail. The presentation should be digestible for a broad range of students.

Bio:

Kristof Croes has an MSc in physics and biostatistics. He obtained a PhD concerning the development of statistical techniques for planning reliability experiments. For seven years, he was product and application manager of the package level reliability products of the Singaporean based company Chiron holdings. Beginning 2007, he went back to research, where he is currently scientific director and group leader of the reliability group working on the reliability of advanced devices, interconnects and packages. Kristof was an (invited/tutorial) speaker at several leading-edge semi-conductor conferences [IEEE International Reliability Physics Symposium (IRPS), IEEE International Interconnect Technology Conference (IITC), and IEEE International Electron Devices Meeting (IEDM)]. He also (co) authored more than 100 articles in the field of reliability.